

General Purpose Transistor Array One Differentially Connected Pair and Three Isolated Transistor Arrays

The MC3346 is designed for general purpose, low power applications for consumer and industrial designs.

- Guaranteed Base-Emitter Voltage Matching
- \bullet Operating Current Range Specified: 10 μA to 10 mA
- Five General Purpose Transistors in One Package

MC3346

GENERAL PURPOSE TRANSISTOR ARRAY

SEMICONDUCTOR TECHNICAL DATA





D SUFFIXPLASTIC PACKAGE
CASE 751A
(SO-14)

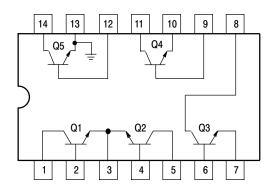
MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-EmitterVoltage	V _{CEO}	15	Vdc
Collector-Base Voltage	V _{CBO}	20	Vdc
Emitter-Base Voltage	V _{EB}	5.0	Vdc
Collector–Substrate Voltage	V _{CIO}	20	Vdc
Collector Current – Continuous	I _C	50	mAdc
Total Power Dissipation @ T _A = 25°C Derate above 25°C	P _D	1.2 10	W mW/°C
Operating Temperature Range	T _A	-40 to +85	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C

ORDERING INFORMATION

Device	Operating Temperature Range	Package
MC3346D	$T_A = -40^{\circ} \text{ to } +85^{\circ}\text{C}$	SO-14
MC3356P	1A = -40 to +65 C	Plastic DIP

PIN CONNECTIONS



Pin 13 is connected to substrate and must remain at the lowest circuit potential.

ELECTRICAL CHARACTERISTICS (T_A = +25°C, unless otherwise noted.)

Characteristics	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTICS					
Collector–Base Breakdown Voltage ($I_C = 10 \mu Adc$)	V _{(BR)CBO}	20	60	-	Vdc
Collector–Emitter Breakdown Voltage (I _C = 1.0 mAdc)	V _{(BR)CEO}	15	_	-	Vdc
Collector–Substrate Breakdown Voltage (I _C = 10 μA)	V _{(BR)CIO}	20	60	-	Vdc
Emitter–Base Breakdown Voltage (I _E = 10 µAdc)	V _{(BR)EBO}	5.0	7.0	-	Vdc
Collector–Base Cutoff Current (V _{CB} = 10 Vdc, I _E = 0)	I _{CBO}	_	-	40	nAdc
DC Current Gain	h _{FE}				_
$(I_C = 10 \text{ mAdc}, V_{CE} = 3.0 \text{ Vdc})$		_	140	_	
$(I_C = 1.0 \text{ mAdc}, V_{CE} = 3.0 \text{ Vdc})$		40	130	-	
$(I_C = 10 \mu Adc, V_{CE} = 3.0 Vdc)$		_	60		
Base–Emitter Voltage	V _{BE}				Vdc
$(V_{CE} = 3.0 \text{ Vdc}, I_{E} = 1.0 \text{ mAdc})$		_	0.72	_	
$(V_{CE} = 3.0 \text{ Vdc}, I_{E} = 10 \text{ mAdc})$		_	0.8	-	
Input Offset Current for Matched Pair Q1 and Q2 (V _{CE} = 3.0 Vdc, I _C = 1.0 mAdc)	I _{IO1} - I _{IO2}	_	0.3	2.0	μAdo
Magnitude of Input Offset Voltage (V _{CE} = 3.0 Vdc, I _C = 1.0 mAdc)	-	_	0.5	5.0	mVdd
Temperature Coefficient of Base–Emitter Voltage (V _{CE} = 3.0 Vdc, I _C = 1.0 mAdc)	$\frac{\Delta V_{BE}}{DT}$	_	-1.9	-	mV/°0
Temperature Coefficient	ΙΔV _{ΙΟ} Ι	_	1.0	_	μV/° (
	DT				
Collector–Emitter Cutoff Current $(V_{CE} = 10 \text{ Vdc}, I_B = 0)$	I _{CEO}	_	_	0.5	μAdo
DYNAMIC CHARACTERISTICS					•
Low Frequency Noise Figure ($V_{CE} = 3.0 \text{ Vdc}, I_{C} = 100 \mu\text{Adc}, R_{S} = 1.0 \text{k}\Omega, f = 1.0 \text{kHz}$)	NF	_	3.25	-	dB
Forward Current Transfer Ratio $(V_{CE} = 3.0 \text{ Vdc}, I_C = 1.0 \text{ mAdc}, f = 1.0 \text{ kHz})$	h _{FE}	_	110	-	_
Short Circuit Input Impedance (V _{CE} = 3.0 Vdc, I _C = 1.0 mAdc)	h _{ie}	_	3.5	-	kΩ
Open Circuit Output Impedance ($V_{CE} = 3.0 \text{ Vdc}, I_{C} = 1.0 \text{ mAdc}$)	h _{oe}	_	15.6	-	μmho
Reverse Voltage Transfer Ratio $(V_{CE} = 3.0 \text{ Vdc}, I_C = 1.0 \text{ mAdc})$	h _{re}	_	1.8	-	x10
Forward Transfer Admittance ($V_{CE} = 3.0 \text{ Vdc}$, $I_C = 1.0 \text{ mAdc}$, $f = 1.0 \text{ MHz}$)	Уfе	_	31–j1.5	-	_
Input Admittance ($V_{CE} = 3.0 \text{ Vdc}$, $I_{C} = 1.0 \text{ mAdc}$, $f = 1.0 \text{ MHz}$)	Уie	_	0.3 + j0.04	-	_
Output Admittance ($V_{CE} = 3.0 \text{ Vdc}$, $I_{C} = 1.0 \text{ mAdc}$, $f = 1.0 \text{ MHz}$)	Уое	_	0.001 + j0.03	-	_
Current–Gain – Bandwidth Product ($V_{CE} = 3.0 \text{ Vdc}, I_{C} = 3.0 \text{ mAdc}$)	f _T	300	550	-	MHz
Emitter–Base Capacitance $(V_{EB} = 3.0 \text{ Vdc}, I_E = 0)$	C _{eb}	_	0.6	-	pF
Collector–Base Capacitance ($V_{CB} = 3.0 \text{ Vdc}, I_{C} = 0$)	C _{cb}	_	0.58	-	pF
Collector–Substrate Capacitance (V _{CS} = 3.0 Vdc, I _C = 0)	C _{Cl}	_	2.8	_	pF

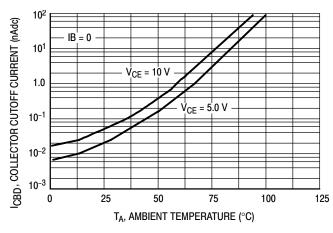


Figure 1. Collector Cutoff Current versus Temperature (Each Transistor)

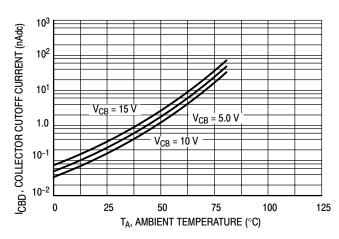


Figure 2. Collector Cutoff Current versus Temperature (Each Transistor)

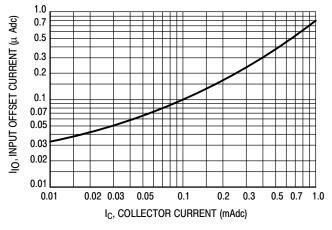


Figure 3. Input Offset Characteristics for Q1 and Q2

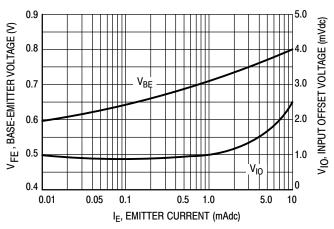


Figure 4. Base–Emitter and Input Offset Voltage Characteristics

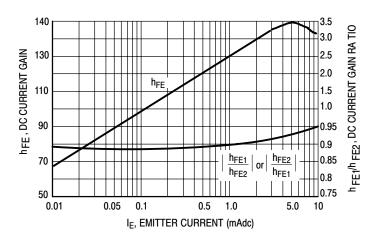
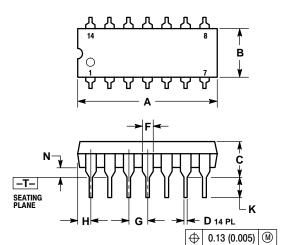


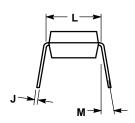
Figure 5. DC Current Gain

PACKAGE DIMENSIONS

P SUFFIX

PLASTIC PACKAGE CASE 646-06 ISSUE M





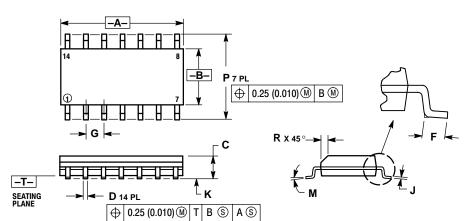
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L'TO CENTER OF LEADS WHEN FORMED PARALLEL
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	18.80	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100 BSC		2.54 BSC		
Н	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.290	0.310	7.37	7.87	
M		10°		10°	
N	0.015	0.039	0.38	1.01	

PACKAGE DIMENSIONS

D SUFFIX

PLASTIC PACKAGE CASE 751A-03 (SO-8) ISSUE F



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0°	7°	0°	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

Notes

Notes

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